·询"SN54LS245-SP"供应商

SDLS146A – OCTOBER 1976 – REVISED FEBRUARY 2002

- 3-State Outputs Drive Bus Lines Directly
- PNP Inputs Reduce dc Loading on Bus Lines
- Hysteresis at Bus Inputs Improves Noise Margins
- Typical Propagation Delay Times Port to Port, 8 ns

TYPE	I _{OL} (SINK CURRENT)	IOH (SOURCE CURRENT) –12 mA				
SN54LS245	12 mA	−12 mA				
SN74LS245	24 mA	–15 mA				

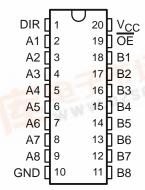
description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

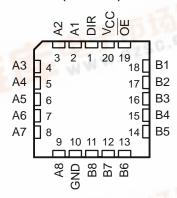
WWW.D

The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can disable the device so that the buses are effectively isolated.

SN54LS245 . . . J OR W PACKAGE SN74LS245 . . . DB, DW, N, OR NS PACKAGE (TOP VIEW)



SN54LS245 . . . FK PACKAGE (TOP VIEW)



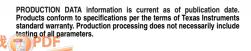
ORDERING INFORMATION

TA	PAC	(AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube SN74LS245N		SN74LS245N
	SOIC - DW	Tube	SN74LS245DW	LS245
0°C to 70°C	SOIC - DW	Tape and reel	SN74LS245DWR	L3245
EB:	SOP - NS	Tape and reel	SN74LS245NSR	74LS245
THE WW	SSOP – DB Tape and ree		SN74LS245DBR	LS245
	CDIP – J	Tube	SN54LS245J	SN54LS245J
–55°C to 125°C	CDIF = 3	Tube	SNJ54LS245J	SNJ54LS245J
-55°C 10 125°C	CFP – W	Tube	SNJ54LS245W	SNJ54LS245W
	LCCC - FK Tube		SN54LS245FK	SN54LS245FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





FUNCTION TABLE

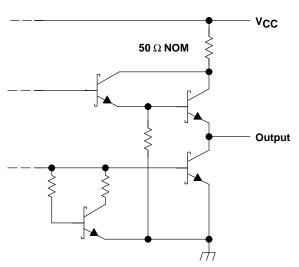
INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation

schematics of inputs and outputs

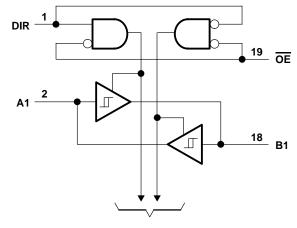
VCC 9 kΩ NOM

EQUIVALENT OF EACH INPUT

TYPICAL OF ALL OUTPUTS



logic diagram (positive logic)



To Seven Other Channels



SDLS146A - OCTOBER 1976 - REVISED FEBRUARY 2002

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}		7 \
Input voltage, V _I (see Note 1)		7 \
Package thermal impedance, θ_{JA} (see Note 2):	DB package	70°C/V
	DW package	58°C/V
	N package	69°C/W
	NS package	60°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

NOTES: 1. All voltage values are with respect to GND.

recommended operating conditions

		SI	N54LS24	5	SI	174LS24	5	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
ІОН	High-level output current			-12			-15	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SN54LS245, SN74LS245 **OCTAL BUŚ TRANSCEIVERS WITH 3-STATE OUTPUTS**

SDLSZEGAT ON OBERCI 976 - REDVISED FIFE BRUARY 2002

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					SI	N54LS24	15	SI	N74LS24	15	
	PARAMET	ΓER	TEST CONI	DITIONST	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input v	oltage			2			2			V
VIL	Low-level input vo	oltage					0.7			0.8	V
VIK	Input clamp voltag	ge	$V_{CC} = MIN,$	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
	Hysteresis (V _{T+} -	- V _T _) A or B	V _{CC} = MIN		0.2	0.4		0.2	0.4		V
V	High lovel output	voltogo	V _{CC} = MIN,	$I_{OH} = -3 \text{ mA}$	2.4	3.4		2.4	3.4		V
VOH	High-level output	voltage	$V_{IH} = 2 V,$ $V_{IL} = V_{IL(max)}$	I _{OH} = MAX	2			2			V
V/01	Low-level output v	voltago	VCC = MIN,	I _{OL} = 12 mA			0.4			0.4	V
VOL	Low-level output	vollage	$V_{IH} = 2 V,$ $V_{IL} = V_{IL(max)}$	I _{OL} = 24 mA						0.5	V
lozh	Off-state output c high-level voltage	•	$\frac{V_{CC}}{OE} = MAX,$	V _O = 2.7 V			20			20	μА
lozL	Off-state output c		$\frac{V_{CC}}{OE} = MAX,$ OE at 2 V	V _O = 0.4 V			-200			-200	μА
1.	Input current at	A or B	\/ NAAV	V _I = 5.5 V			0.1			0.1	mA
l II	maximum input voltage	DIR or OE	VCC = MAX	V _I = 7 V			0.1			0.1	IIIA
lн	High-level input c	urrent	$V_{CC} = MAX$,	V _{IH} = 2.7 V			20			20	μΑ
IIL	Low-level input cu	w-level input current		V _{IL} = 0.4 V			-0.2			-0.2	mA
los	Short-circuit outpo	ut current§	$V_{CC} = MAX$		-40		-225	40		-225	mA
		Total, outputs high				48	70		48	70	
ICC	Supply current	Total, outputs low	V _{CC} = MAX	Outputs open		62	90		62	90	mA
		Outputs at high Z				64	95		64	95	

[†] For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

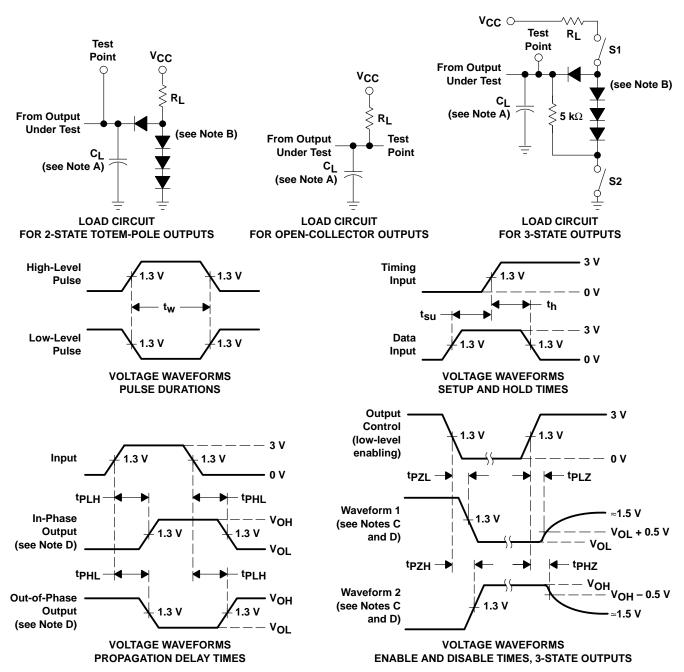
switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	0 45 -5	D 007.0		8	12	
tPHL	Propagation delay time, high- to low-level output	$C_L = 45 \text{ pF},$	$R_L = 667 \Omega$		8	12	ns
tPZL	Output enable time to low level	C _I = 45 pF,	D: -667.0		27	40	no
tPZH	Output enable time to high level	OL = 45 pr,	$R_L = 667 \Omega$		25	40	ns
tPLZ	Output disable time from low level	$C_1 = 5 pF$,	R _I = 667 Ω		15	25	ne
tPHZ	Output disable time from high level	С _L = 5 рг,	K[= 007 \$2		15	28	ns



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION SERIES 54LS/74LS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 - B. All diodes are 1N3064 or equivalent.
 - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - D. S1 and S2 are closed for tpLH, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
 - E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
 - F. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z $_{0} \approx$ 50 Ω , $t_{f} \leq$ 1.5 ns, $t_{f} \leq$ 2.6 ns.
 - G. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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15-Oct-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾			
5962-8002101VRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type			
5962-8002101VSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type			
80021012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type			
8002101SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type			
JM38510/32803B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type			
JM38510/32803BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type			
JM38510/32803BSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type			
SN54LS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type			
SN74LS245DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM			
SN74LS245DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM			
SN74LS245DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	CU NIPDAU	CU NIPDAU	CU NIPDAU	Level-1-260C-UNLIM
SN74LS245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM			
SN74LS245DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM			
SN74LS245DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM			
SN74LS245DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM			
SN74LS245J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI			
SN74LS245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type			
SN74LS245N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI			
SN74LS245NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type			
SN74LS245NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM			
SN74LS245NSRE4	ACTIVE	SO	NS	20			CU NIPDAU	Level-1-260C-UNLIM			
SN74LS245NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM			
SNJ54LS245FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type			
SNJ54LS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type			
SNJ54LS245W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type			

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs. **LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

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15-Oct-2009

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

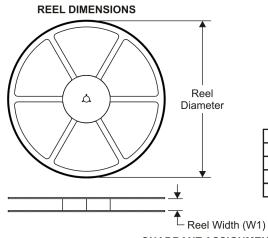
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

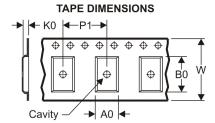
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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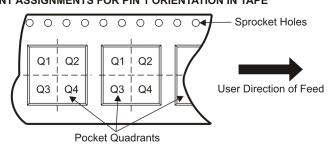
TAPE AND REEL INFORMATION





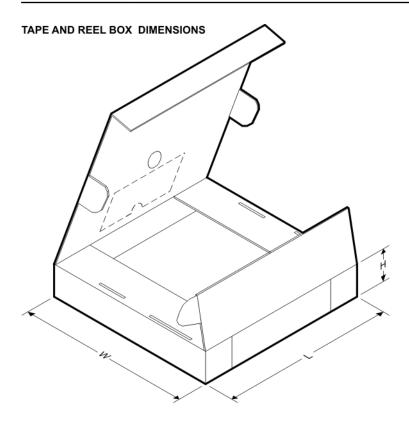
	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS245DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LS245DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74LS245NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS245DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74LS245DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74LS245NSR	SO	NS	20	2000	346.0	346.0	41.0

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

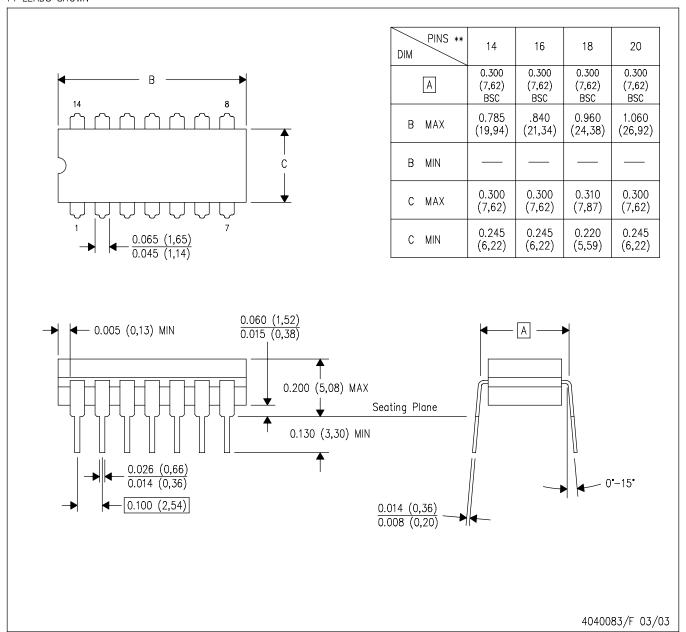
D. Falls within JEDEC MO-150

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J (R-GDIP-T**)

CERAMIC DUAL IN-LINE PACKAGE

14 LEADS SHOWN



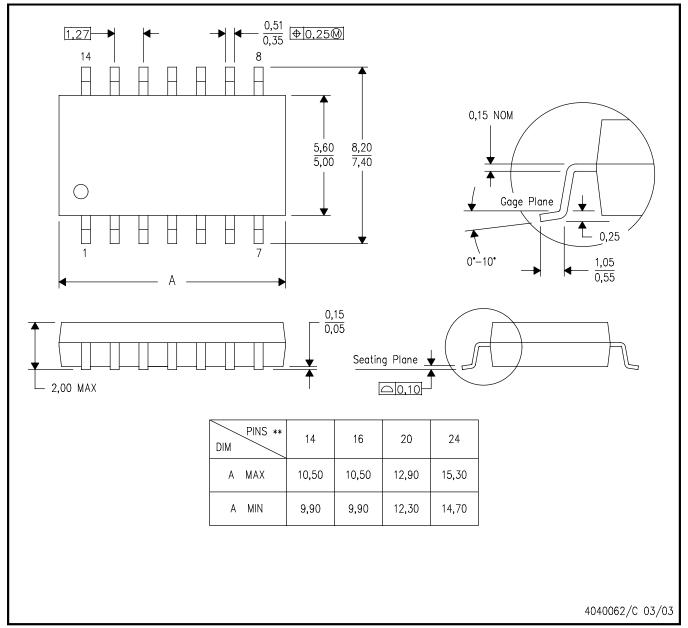
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



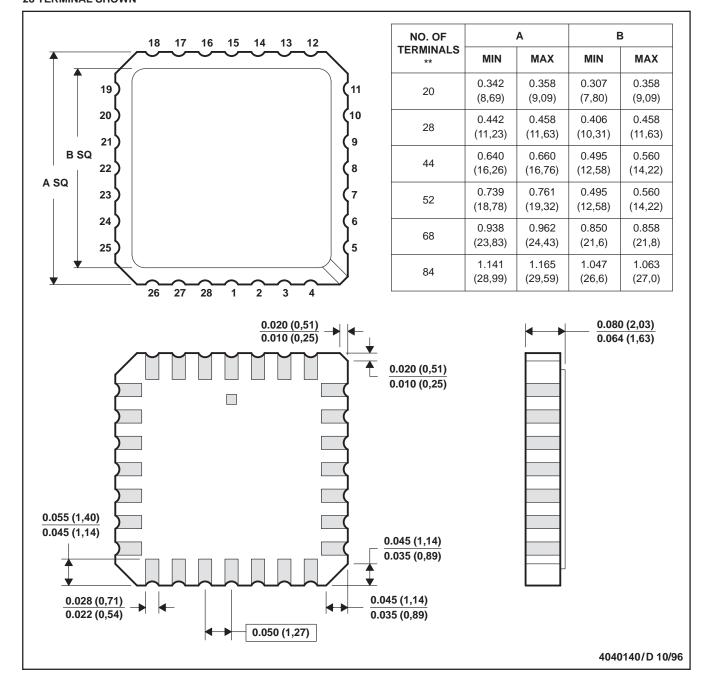
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



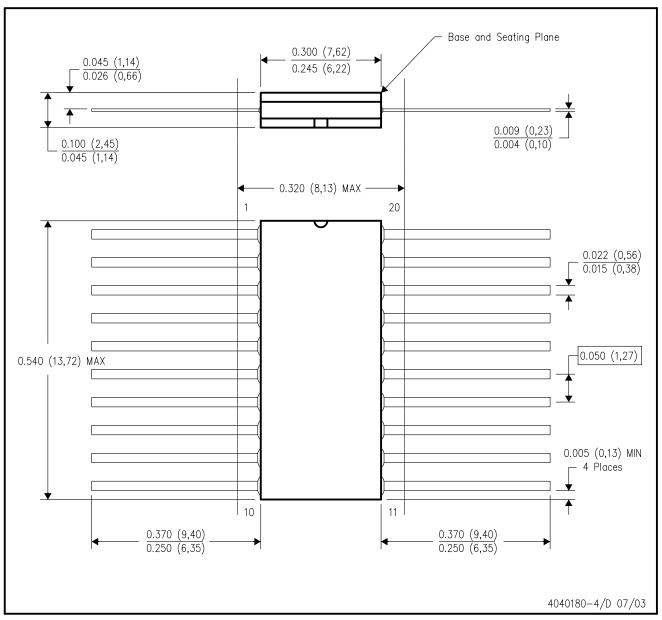
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

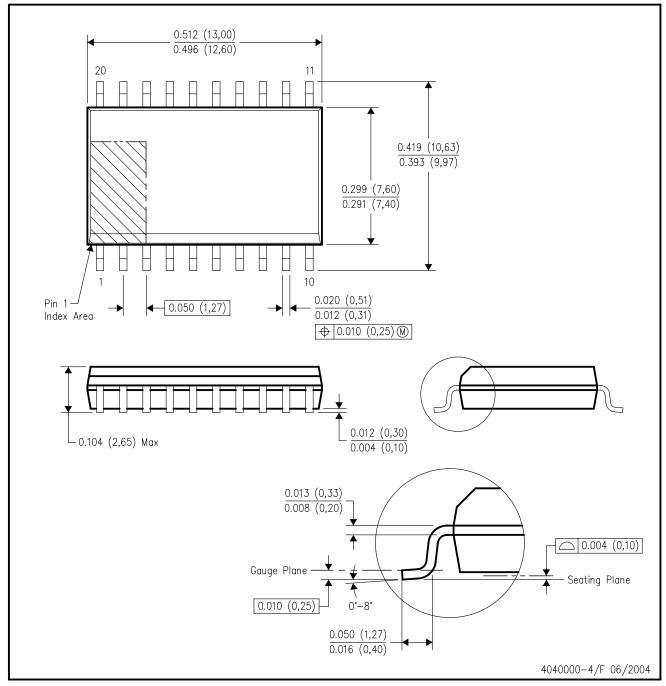


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



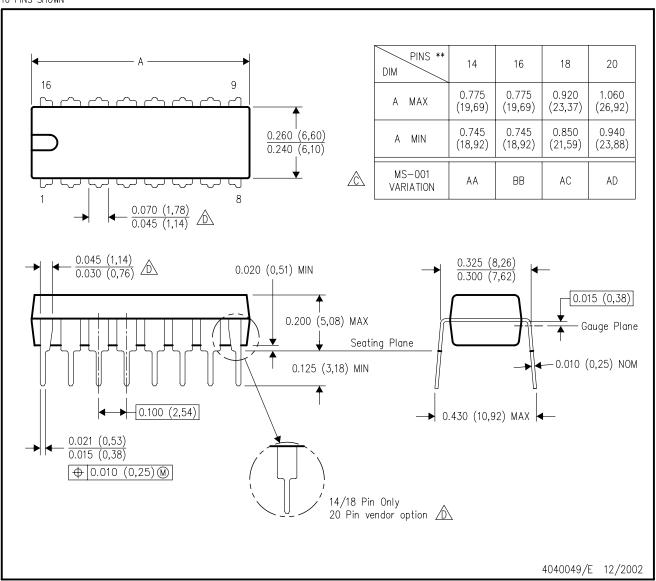
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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